



# 650V Super-junction Power MOSFET

## Description

### 650V Super-junction Power MOSFET

Super-junction power MOSFET is a revolutionary technology for high voltage power MOSFETs, designed according to the SJ principle. The Multi-EPI SJ MOSFET provide an extremely low switching, communication and conduction losses device with highest robustness make especially resonant switching applications more reliable, more efficient, lighter and cooler, designed by Wuxi Unigroup Microelectronics Company.

## Features

- Very low FOM  $R_{DS(on)} \times Q_g$
- 100% avalanche tested
- Easy to use/drive
- RoHS compliant

## Applications

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)
- Charger

TO-220F



TO-263



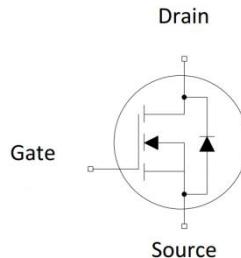
TO-220



TO-220FP-NL



Drain



## Device Marking and Package Information

Device	Package	Marking
TPA65R260M	TO-220F	65R260M
TPB65R260M	TO-263	65R260M
TPP65R260M	TO-220	65R260M
TPR65R260M	TO-220FP-NL	65R260M

## Key Performance Parameters

Parameter	Value	Unit
$V_{DS} @ T_{j,max}$	700	V
$R_{DS(on),max}$	0.26	$\Omega$
$Q_{g,typ}$	27	nC
$I_D$	15	A
$I_{D,pulse}$	45	A
$E_{oss} @ 400V$	3.47	$\mu J$
Body Diode $di_F/dt$	500	$A/\mu s$

**Absolute Maximum Ratings  $T_C = 25^\circ\text{C}$ , unless otherwise noted**

Parameter	Symbol	Value	Unit
Continuous Drain Current $T_C = 25^\circ\text{C}$	$I_D$	15	A
$T_C = 100^\circ\text{C}$		9	
Pulsed Drain Current (note1)	$I_{D,\text{pulse}}$	45	A
Gate-Source Voltage	$V_{GSS}$	$\pm 30$	V
Single Pulse Avalanche Energy (note2)	$E_{AS}$	290	mJ
Repetitive Avalanche Energy (note2)	$E_{AR}$	0.44	mJ
Avalanche Current	$I_{AR}$	2.4	A
MOSFET dv/dt Ruggedness, $V_{DS} = 0 \dots 480\text{V}$	dv/dt	50	V/ns
Power Dissipation For TO-220F,TO-220FP-NL	$P_D$	32	W
Power Dissipation For TO-263,TO-220		105	
Continuous Body Diode Current	$I_S$	12.8	A
Diode Pulsed Current (note1)	$I_{S,\text{pulse}}$	45	
Reverse Diode dv/dt (note3)	dv/dt	15	V/ns
Maximum Diode Commutation Speed (note3)	di/dt	500	A/ $\mu\text{s}$
Operating Junction and Storage Temperature Range	$T_J, T_{stg}$	-55~+150	°C

**Thermal Resistance For TO-220F,TO-220FP-NL**

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	$R_{thJC}$	3.9	°C/W
Thermal Resistance, Junction-to-Ambient	$R_{thJA}$	80	

**Thermal Resistance For TO-263,TO-220**

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	$R_{thJC}$	1.2	°C/W
Thermal Resistance, Junction-to-Ambient	$R_{thJA}$	62	

**Electrical Characteristics**  $T_J = 25^\circ\text{C}$ , unless otherwise noted

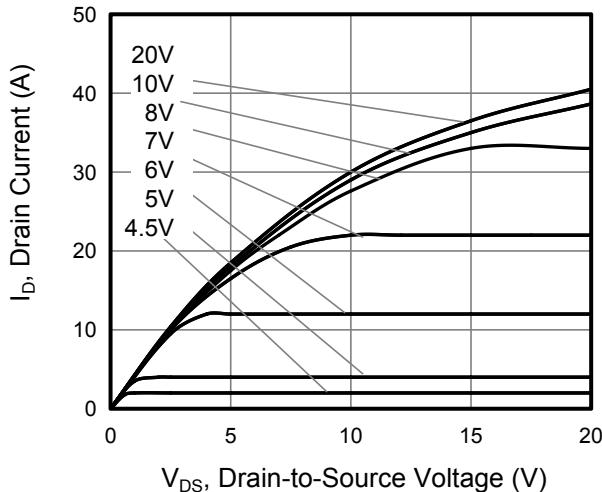
Parameter	Symbol	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
<b>Static Characteristics</b>						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{GS} = 0V, I_D = 250\mu\text{A}$	650	--	--	V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{DS} = 650V, V_{GS} = 0V, T_J = 25^\circ\text{C}$	--	--	1	$\mu\text{A}$
		$V_{DS} = 650V, V_{GS} = 0V, T_J = 150^\circ\text{C}$	--	--	100	
Gate-Source Leakage Current	$I_{GSS}$	$V_{GS} = \pm 30V$	--	--	$\pm 100$	nA
Gate-Source Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	2.5	--	4.5	V
Drain-Source On-State-Resistance	$R_{DS(\text{on})}$	$V_{GS} = 10V, I_D = 7.5\text{A}$	--	0.24	0.26	$\Omega$
Gate Resistance	$R_G$	$f = 1.0\text{MHz}$ open drain	--	12.5	--	$\Omega$
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{iss}$	$V_{GS} = 0V,$ $V_{DS} = 100V,$ $f = 1.0\text{MHz}$	--	1138	--	$\text{pF}$
Output Capacitance	$C_{oss}$		--	40	--	
Reverse Transfer Capacitance	$C_{rss}$		--	2.3	--	
Total Gate Charge	$Q_g$	$V_{DD} = 520V, I_D = 15A,$ $V_{GS} = 10V$	--	27	--	$\text{nC}$
Gate-Source Charge	$Q_{gs}$		--	5.5	--	
Gate-Drain Charge	$Q_{gd}$		--	10.5	--	
Turn-on Delay Time	$t_{d(\text{on})}$	$V_{DD} = 400V, I_D = 15A,$ $R_G = 25\Omega$	--	25	--	$\text{ns}$
Turn-on Rise Time	$t_r$		--	63	--	
Turn-off Delay Time	$t_{d(\text{off})}$		--	100	--	
Turn-off Fall Time	$t_f$		--	50	--	
<b>Drain-Source Body Diode Characteristics</b>						
Body Diode Forward Voltage	$V_{SD}$	$T_J = 25^\circ\text{C}, I_{SD} = 15A, V_{GS} = 0V$	--	0.9	1.2	V
Reverse Recovery Time	$t_{rr}$	$V_R = 400V, I_F = I_S,$ $di_F/dt = 100A/\mu\text{s}$	--	410	--	$\text{ns}$
Reverse Recovery Charge	$Q_{rr}$		--	4.1	--	$\mu\text{C}$
Peak Reverse Recovery Current	$I_{rm}$		--	20	--	A

**Notes**

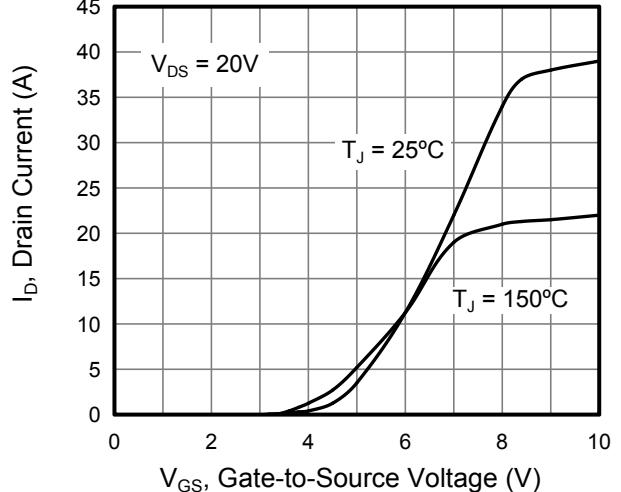
1. Repetitive Rating: Pulse width limited by maximum junction temperature
2.  $I_{AS} = 2.4A, V_{DD} = 50V, R_G = 25\Omega$ , Starting  $T_J = 25^\circ\text{C}$
3. Identical low side and high side switch with identical  $R_G$

**Typical Characteristics**  $T_J = 25^\circ\text{C}$ , unless otherwise noted

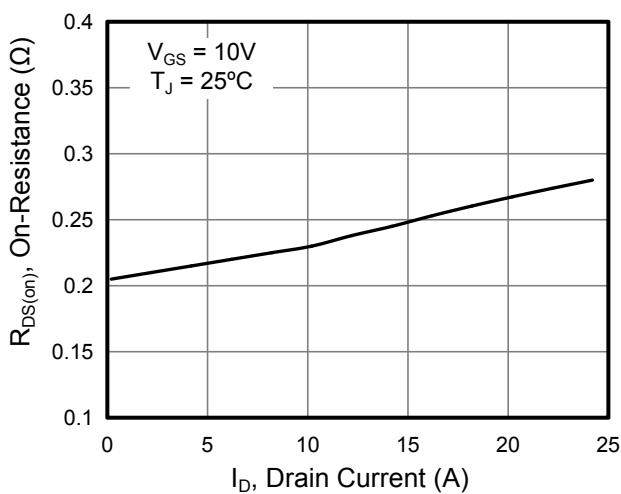
**Figure 1. Output Characteristics**



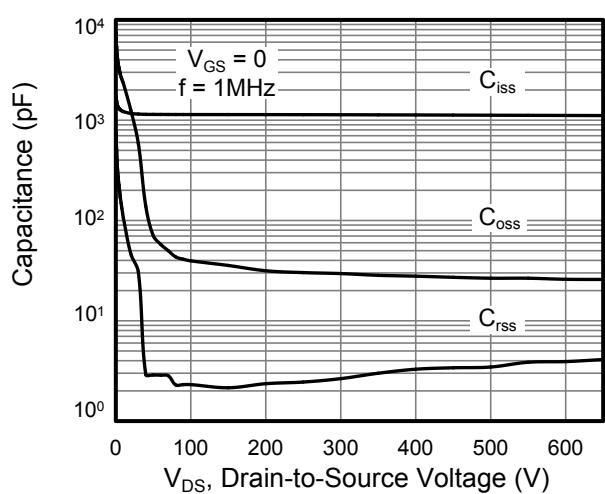
**Figure 2. Transfer Characteristics**



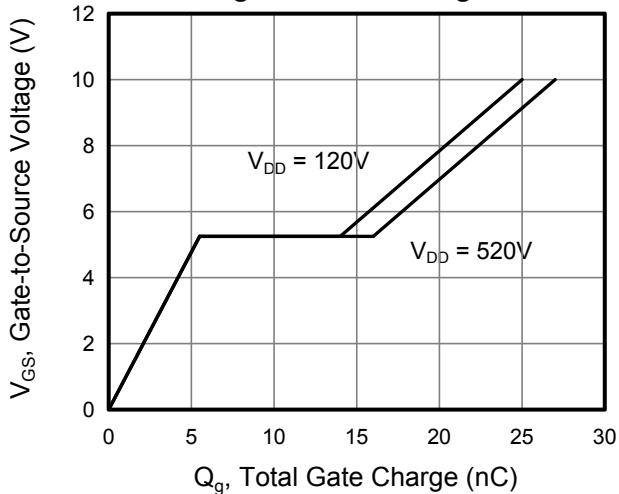
**Figure 3. On-Resistance vs. Drain Current**



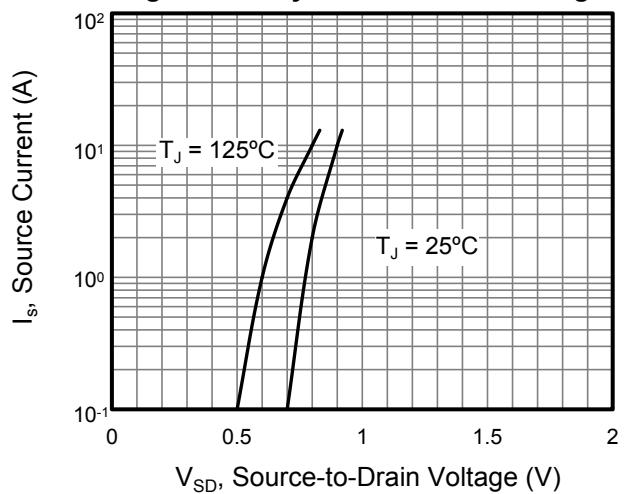
**Figure 4. Capacitance**



**Figure 5. Gate Charge**



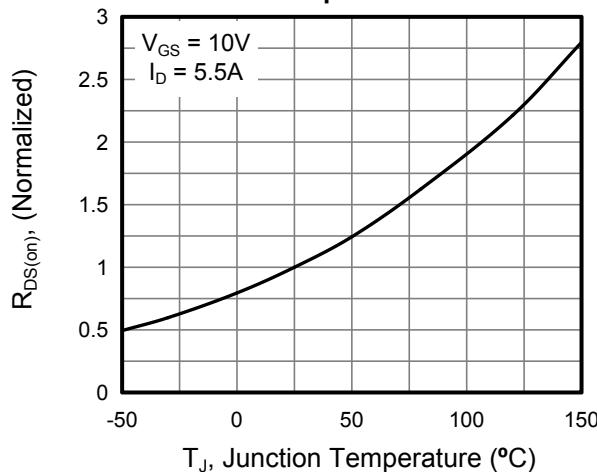
**Figure 6. Body Diode Forward Voltage**



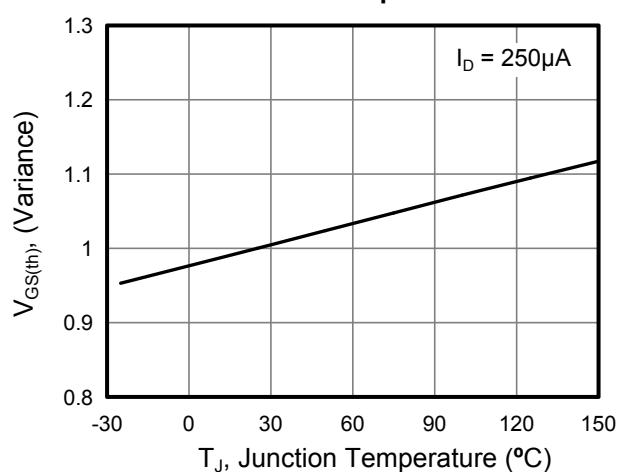


**Typical Characteristics**  $T_J = 25^\circ\text{C}$ , unless otherwise noted

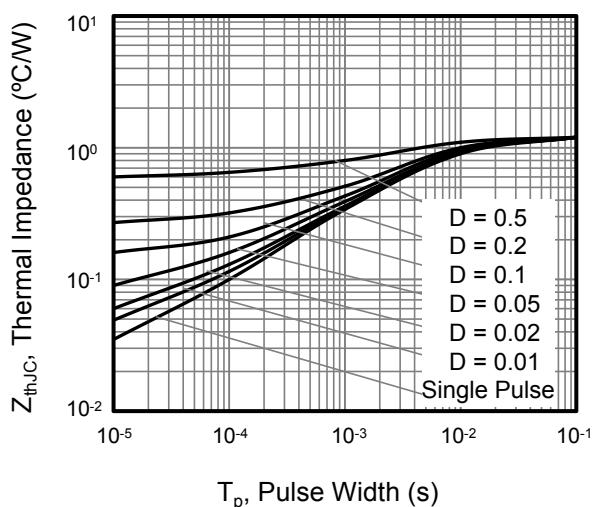
**Figure 7. On-Resistance vs. Temperature**



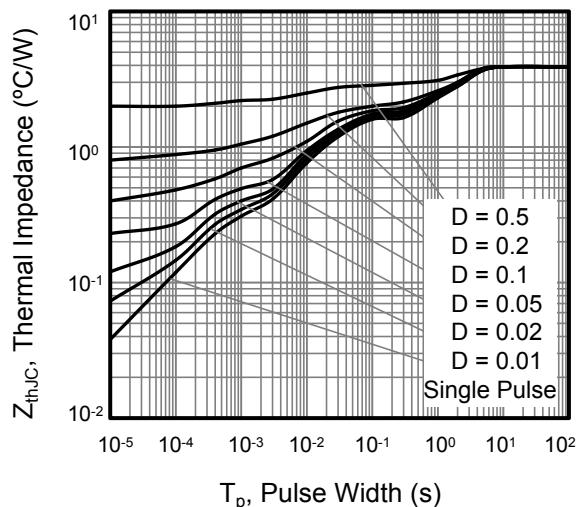
**Figure 8. Breakdown voltage vs. Junction Temperature**



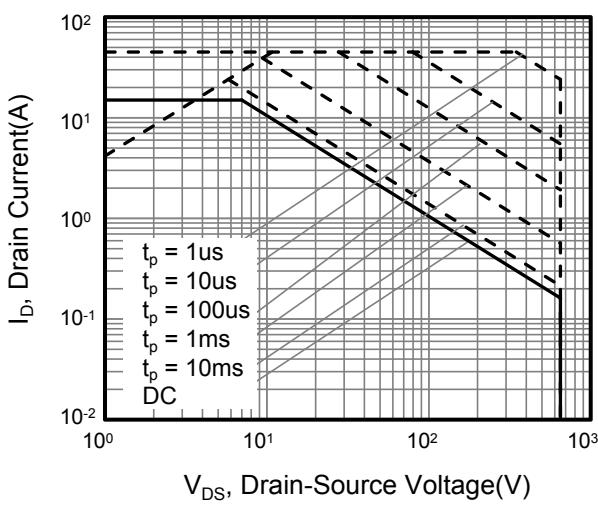
**Figure 9. Transient Thermal Impedance For TO-263/TO-220**



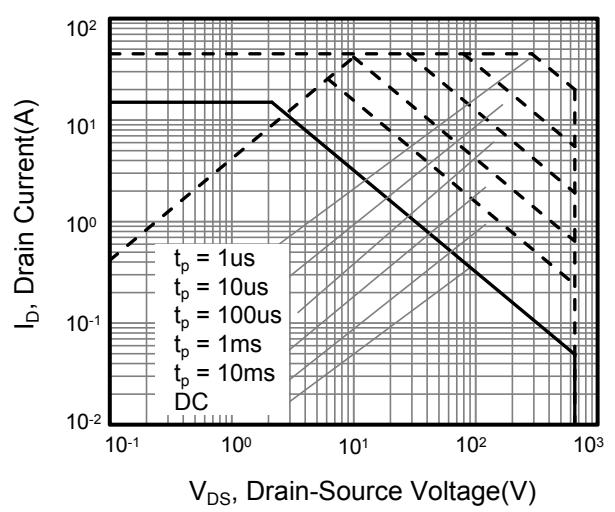
**Figure 10. Transient Thermal Impedance For TO-220F/TO-220FP-NL**



**Figure 11. Safe Operation Area For TO-263/TO-220**



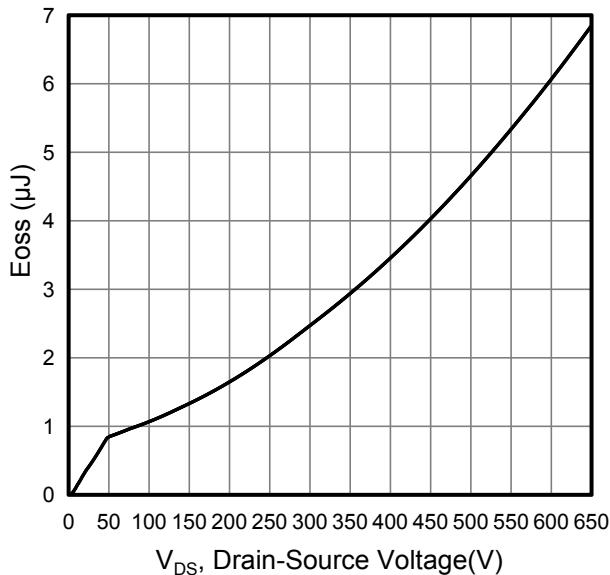
**Figure 12. Safe Operation Area For TO-220F/TO-220FP-NL**

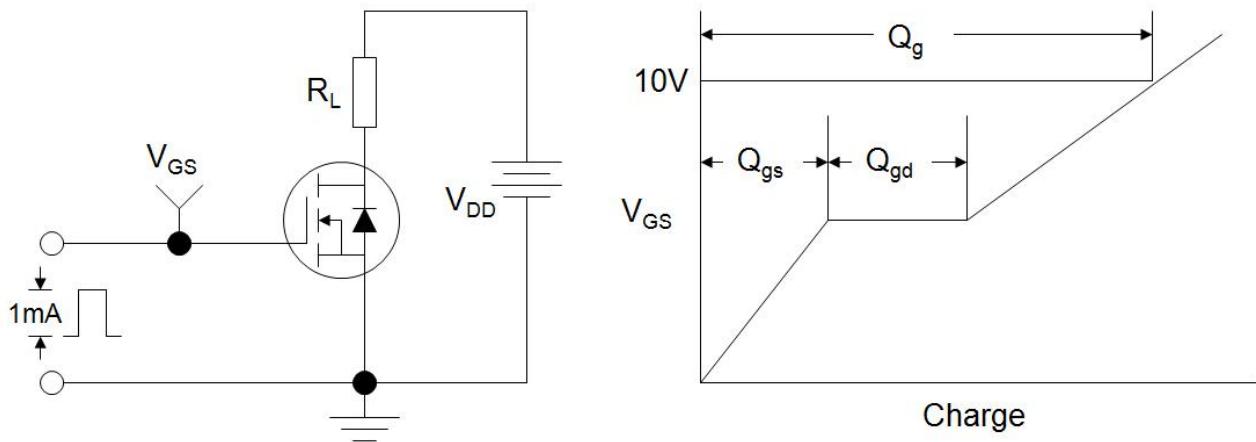
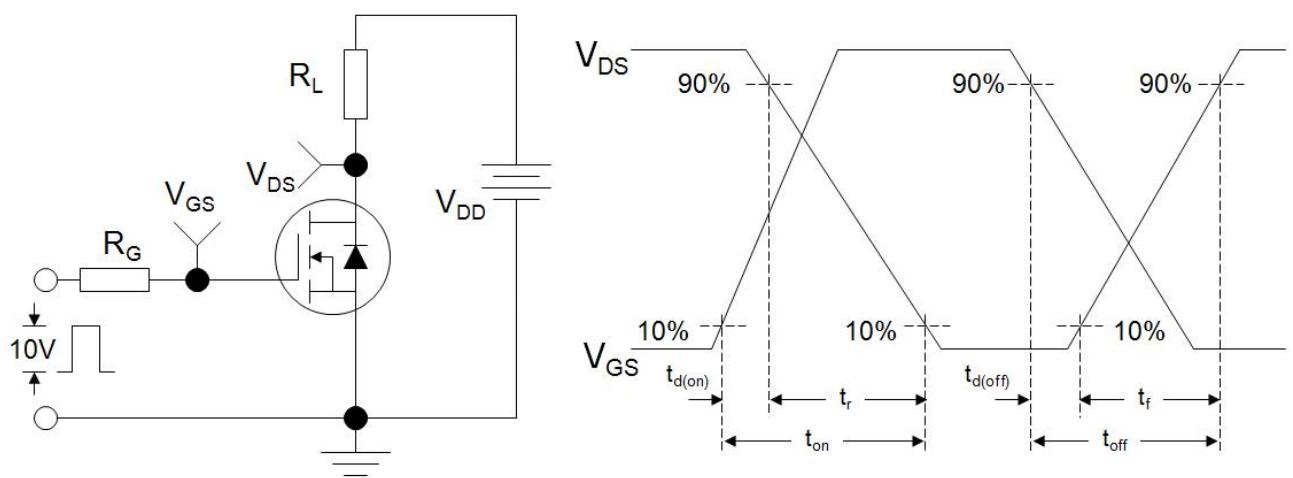
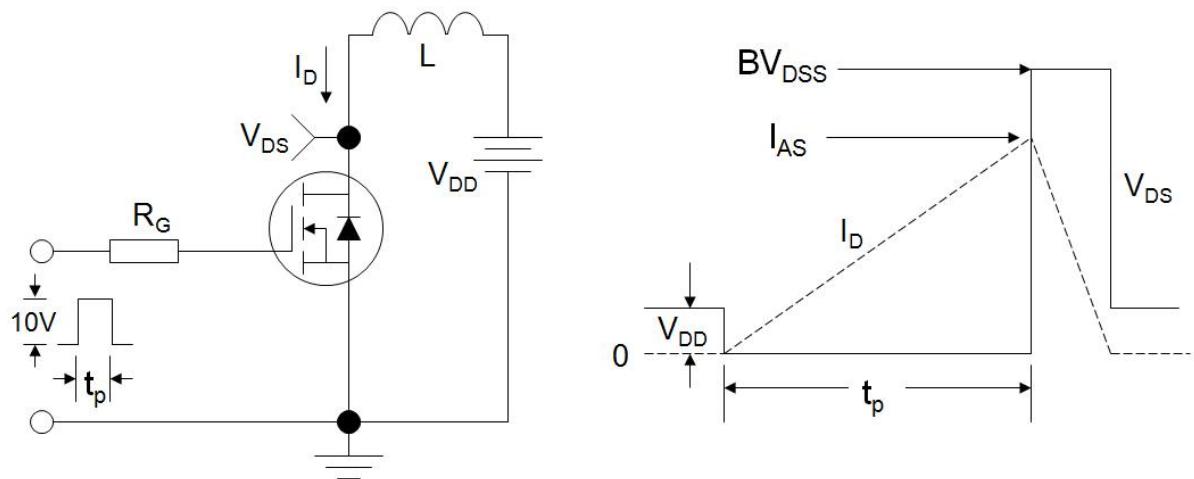




Typical Characteristics  $T_J = 25^\circ\text{C}$ , unless otherwise noted

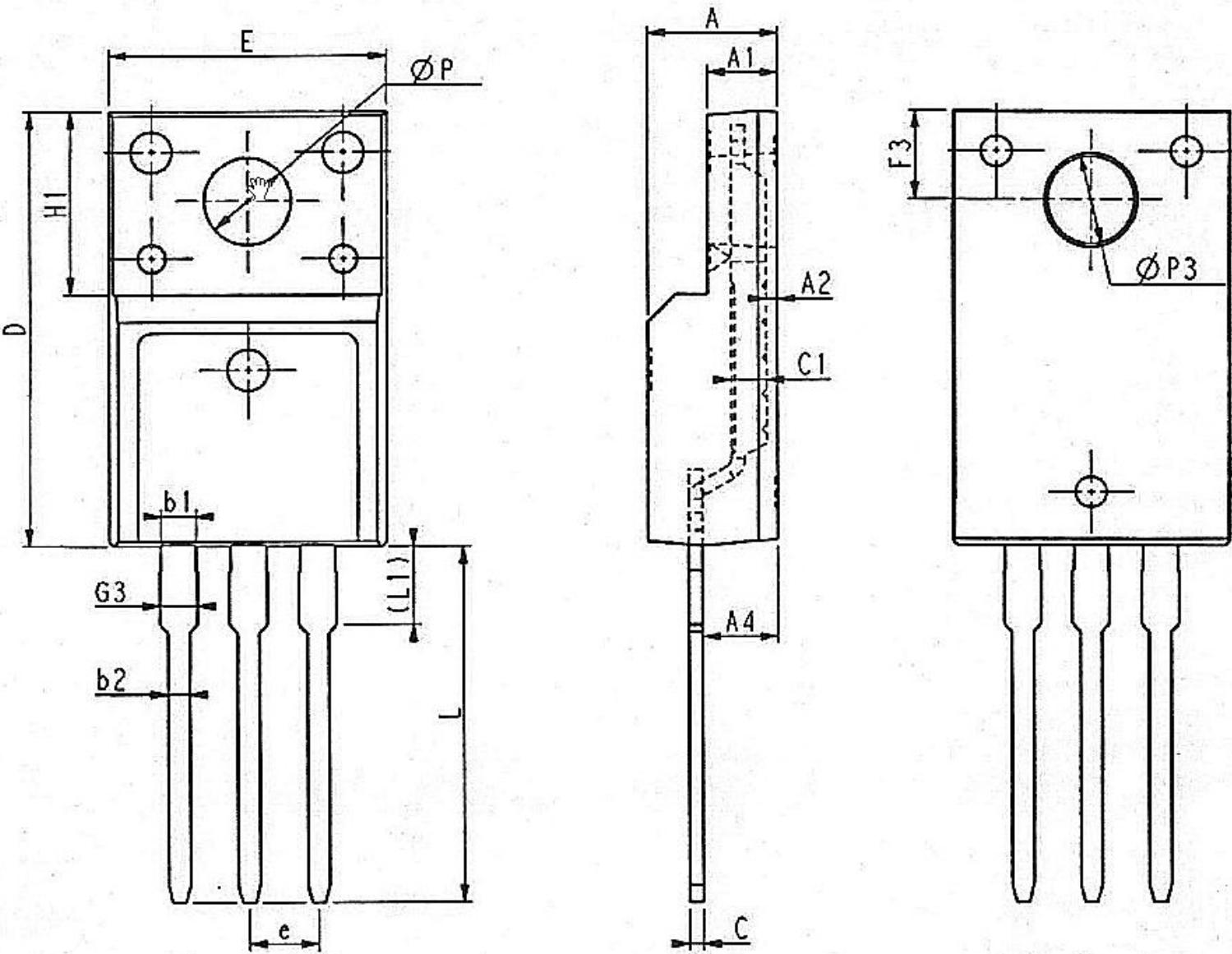
Figure 13. Typ. Coss Stored Energy



**Figure A: Gate Charge Test Circuit and Waveform**

**Figure B: Resistive Switching Test Circuit and Waveform**

**Figure C: Unclamped Inductive Switching Test Circuit and Waveform**




## TO-220F

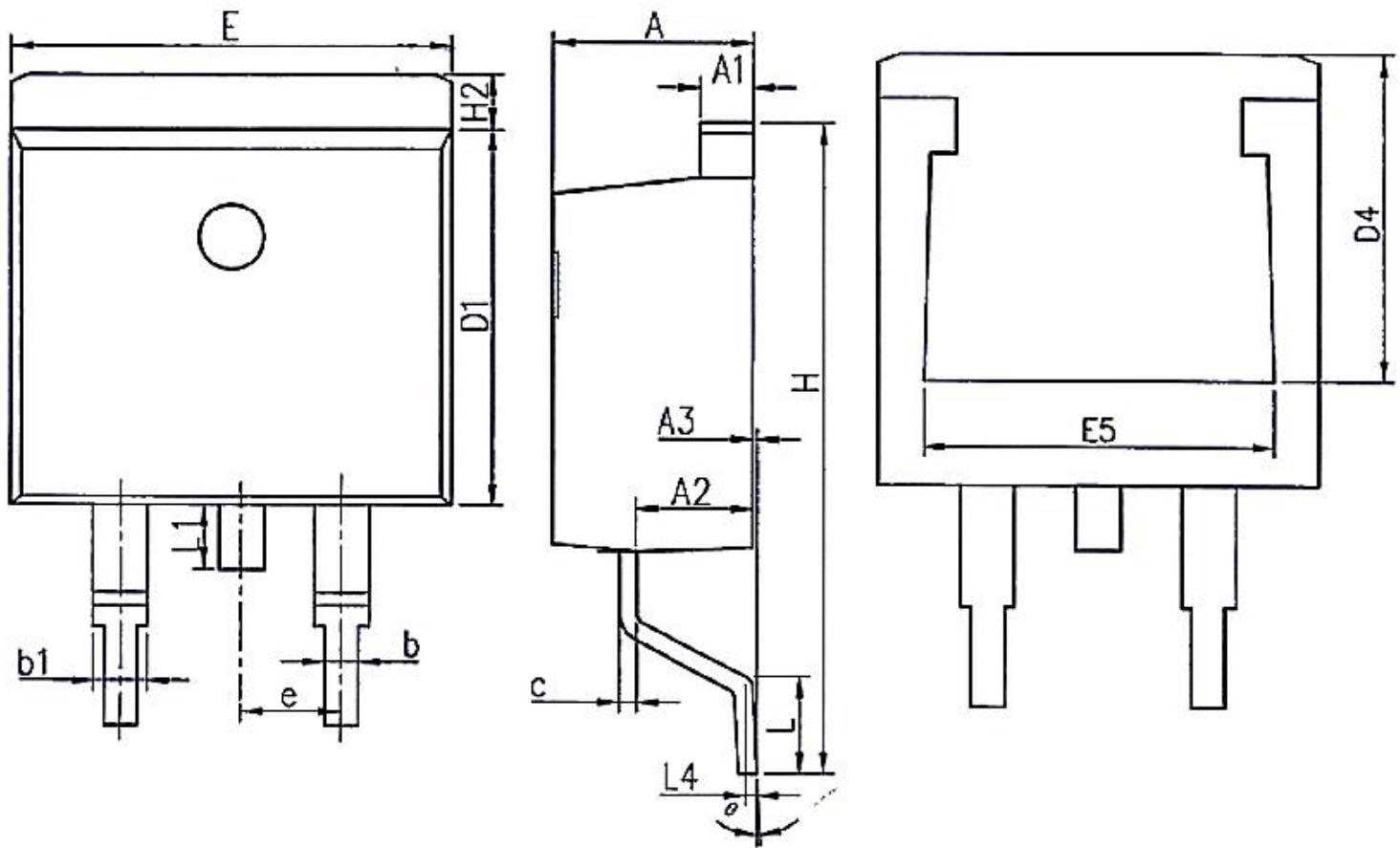


Unit:mm			
Symbol	Min.	Nom	Max.
E	9.96	10.16	10.36
A	4.50	4.70	4.90
A1	2.34	2.54	2.74
A2	0.30	0.45	0.60
A4	2.56	2.76	2.96
c	0.40	0.50	0.65
c1	1.20	1.30	1.35
D	15.57	15.87	16.17
H1	6.70REF		

Unit:mm			
Symbol	Min.	Nom	Max.
e	2.54BSC		
L	12.68	12.98	13.28
L1	2.88	3.03	3.18
ØP	3.03	3.18	3.38
ØP3	3.15	3.45	3.65
F3	3.15	3.30	3.45
G3	1.25	1.35	1.55
b1	1.18	1.28	1.43
b2	0.70	0.80	0.95



## TO-263

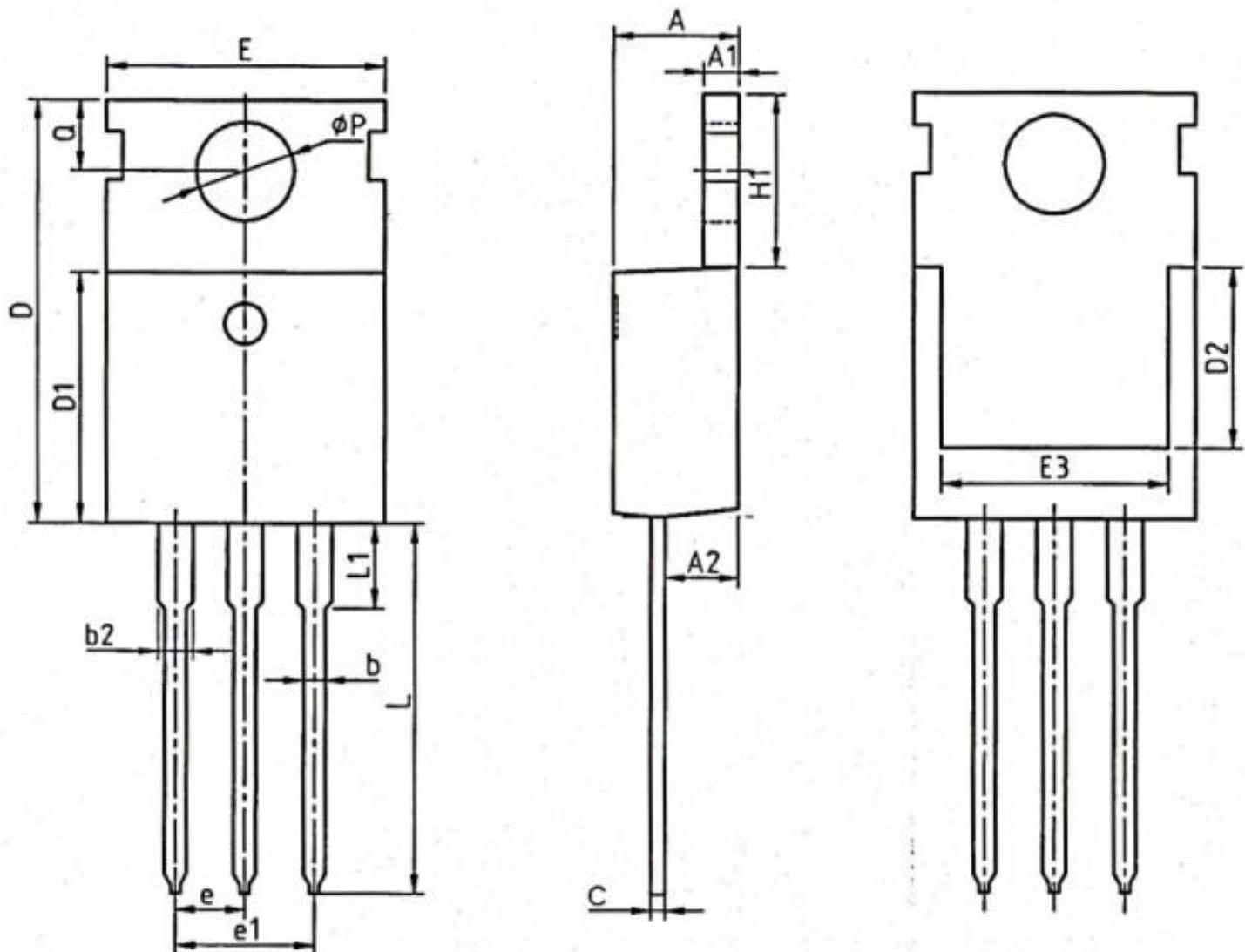


Unit:mm			
Symbol	Min.	Nom	Max.
A	4.37	4.57	4.77
A1	1.22	1.27	1.42
A2	2.49	2.69	2.89
A3	0.00	0.13	0.25
b	0.70	0.81	0.96
b1	1.17	1.27	1.47
c	0.30	0.38	0.53
D1	8.50	8.70	8.90
D4	6.60	-	-

Unit:mm			
Symbol	Min.	Nom	Max.
E	9.86	10.16	10.36
E5	7.06	-	-
e	2.54BSC		
H	14.70	15.10	15.50
H2	1.07	1.27	1.47
L	2.00	2.30	2.60
L1	1.40	1.55	1.70
L4	0.25BSC		
θ	0°	5°	9°



## TO-220

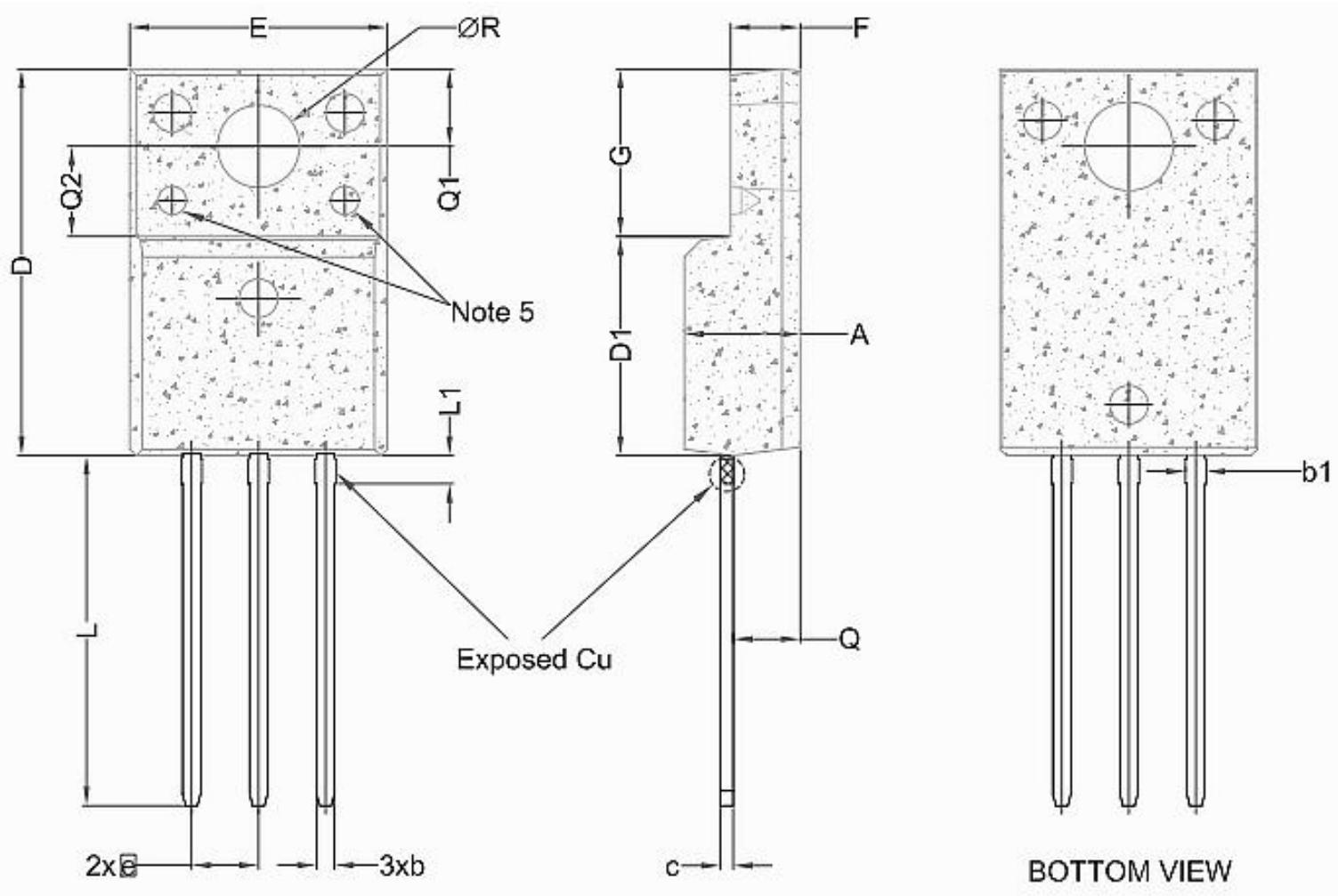


Unit:mm			
Symbol	Min.	Nom	Max.
A	4.37	4.57	4.77
A1	1.25	1.30	1.45
b	2.20	2.40	2.60
b2	1.17	1.27	1.47
c	0.45	0.50	0.60
D	15.10	15.60	16.10
D1	8.80	9.10	9.40
D2	5.50	-	-
E	9.70	10.00	10.30

Unit:mm			
Symbol	Min.	Nom	Max.
E3	7.00	-	-
e	2.54BSC		
e1	5.08BSC		
H1	6.25	6.50	6.85
L	12.75	13.50	13.80
L1	-	3.10	3.40
ΦP	3.40	3.60	3.80
Q	2.60	2.80	3.00



## TO-220FP-NL



Unit:mm			
Symbol	Min.	Nom	Max.
A	4.30	4.50	4.70
b	0.60	0.70	0.80
b1	0.60	0.80	0.90
c	0.45	0.50	0.60
D	14.70	15.00	15.30
D1	8.50 REF		
e	2.60BSC		
E	9.70	10.00	10.30

Unit:mm			
Symbol	Min.	Nom	Max.
F	2.50	2.70	2.90
G	6.30	6.50	6.70
L	13.40	13.60	13.80
L1	1.00	1.10	1.20
Q	2.50	2.60	2.70
Q1	2.90	3.00	3.10
Q2	3.50 REF		
ΦR	3.00	3.20	3.40



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